

## **Product Information Sheet**

MATERIAL ID: EPO-TEK® B9126-8

**Date:** Apr 2010 **Per:** 

Rev: II

Material Description: A single component, thermally and electrically conductive, epoxy adhesive

designed for semiconductor die attach and circuit assembly applications. Its unique features are a pot-life of several days, low temperature cure and syringe dispensing rheology. It can be used for electrical connections when bonding

chips, SMDs, PCBs and substrates.

**Number of Components:** Single Mix Ratio by weight: N/A

**Cure Schedule (minimum)** 150°C/5 Minutes - 120°C/15 Minutes

**Specific Gravity:** 2.92 --- Part A: Part B:

Pot Life: 5 Days

**Shelf Life:** One year refrigerated

NOTE: Container(s) should be kept closed when not in use. Filled systems should be stirred thoroughly before

mixing and prior to use

**MATERIAL CHARACTERISTICS:** To be used as a guide only, not as a specification. Data below is not guaranteed. Different batches, conditions and applications yield differing results; Cure condition: 150°C/1 hour \* denotes test on lot acceptance basis

PHYSICAL PROPERTIES:				
*Color (before cure):	Silver	Weight Loss:		
*Consistency:	Smooth paste	@ 200°C:		
*Viscosity (23°C):		@ 250°C:		
@ 20 <b>rpm</b>	11,000 - 18,500 <b>cPs</b>	@ 300°C:	1.07 %	
Thixotropic Index:	3.2	Operating Temp:		
*Glass Transition Temp:	$\geq$ 60 °C (Dynamic Cure	Continuous:	- 55°C to + 175°C	
20—200°C /ISO 25 Min; Ramp -10—200°C @ 20°C/Min)		Intermittent:	- 55°C to + 275°C	
Coefficient of Thermal Expansion (CTE):		Storage Modulus @ 23°C:	227,897 <b>psi</b>	
	Upon Request	Ion Content:		
		CIT:	80 <b>ppm</b>	
Shore D Hardness:	71	NH <sub>4</sub> <sup>+</sup> :	41 <b>ppm</b>	
Lap Shear @ 23°C:	980 <b>psi</b>	Na <sup>+</sup> :	23 <b>ppm</b>	
Die Shear @ 23°C:	$\geq$ 5 <b>Kg</b> / 1,700 <b>psi</b>	<b>K</b> <sup>+</sup> :	8 <b>ppm</b>	
Degradation Temp:	340 ° <b>C</b>	*Particle Size:	≤ 30 microns	

ELECTRICAL AND THERMAL PROPERTIES:					
Thermal Conductivity:	1.2 <b>W/mK</b>	Dielectric Constant (1KHz):	N/A		
*Volume Resistivity @ 23°C:	≤ 0.0002 <b>Ohm-cm</b>	Dissipation Factor (1KHz):	N/A		

OPTICAL PROPERTIES @ 23°C:				
Spectral Transmission: N/A	Index of Refraction:	N/A		

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